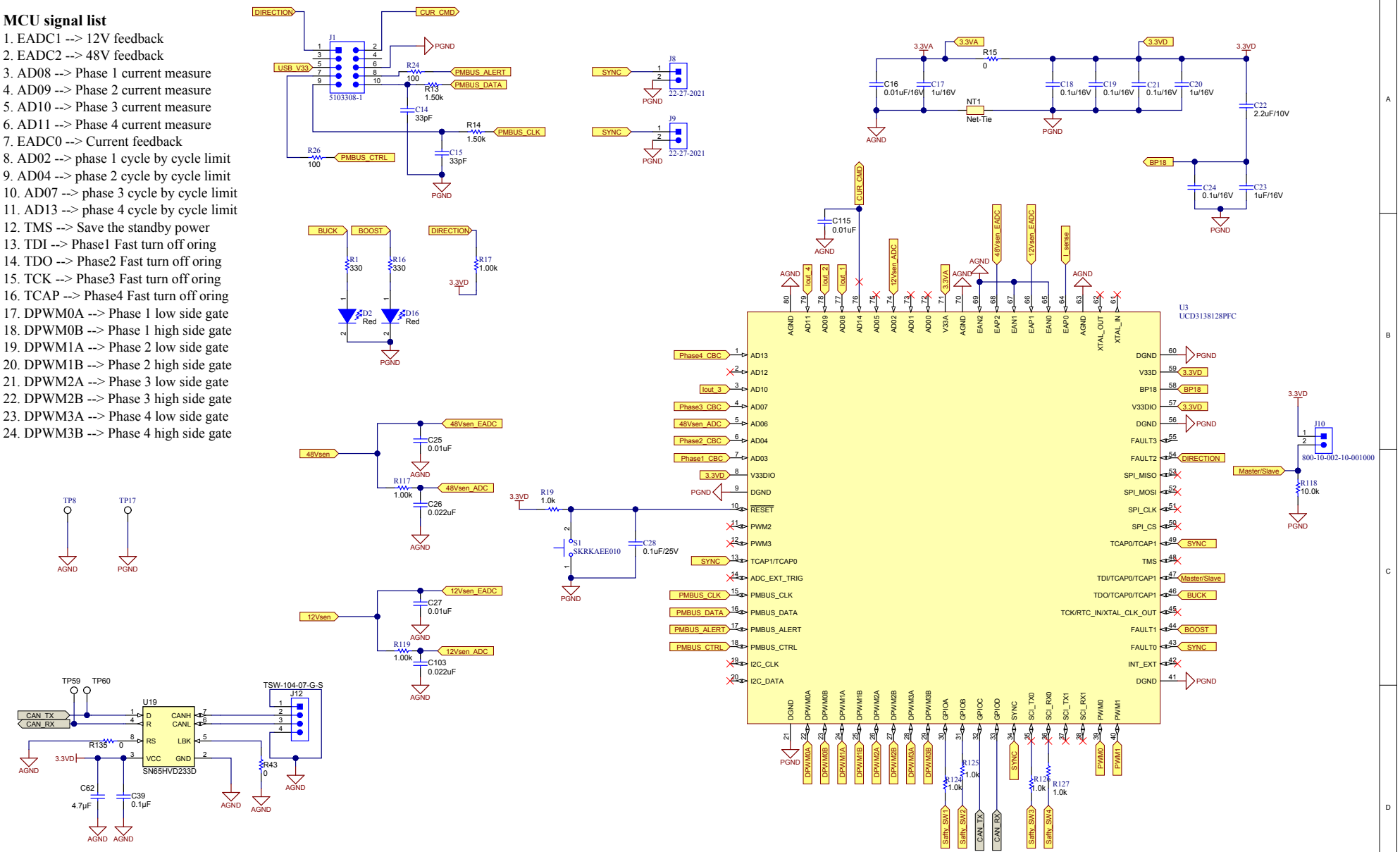
MCU signal list

1. EADC1 --> 12V feedback
2. EADC2 --> 48V feedback
3. AD08 --> Phase 1 current measure
4. AD09 --> Phase 2 current measure
5. AD10 --> Phase 3 current measure
6. AD11 --> Phase 4 current measure
7. EADC0 --> Current feedback
8. AD02 --> phase 1 cycle by cycle limit
9. AD04 --> phase 2 cycle by cycle limit
10. AD07 --> phase 3 cycle by cycle limit
11. AD13 --> phase 4 cycle by cycle limit
12. TMS --> Save the standby power
13. TDI --> Phase1 Fast turn off oring
14. TDO --> Phase2 Fast turn off oring
15. TCK --> Phase3 Fast turn off oring
16. TCAP --> Phase4 Fast turn off oring
17. DPWM0A --> Phase 1 low side gate
18. DPWM0B --> Phase 1 high side gate
19. DPWM1A --> Phase 2 low side gate
20. DPWM1B --> Phase 2 high side gate
21. DPWM2A --> Phase 3 low side gate
22. DPWM2B --> Phase 3 high side gate
23. DPWM3A --> Phase 4 low side gate
24. DPWM3B --> Phase 4 high side gate



Designed for: Automotive	Mod. Date: 3/17/2016
Project Title: Bidirectional DCDC converter	
Number: TIDA-00653 Rev: AA1	Sheet Title: MCU
SVN Rev: Not in version control	Assembly Variant: 001 Sheet: 1 of 6
Drawn By:	File: bidirectional-MCU.SchDoc Size: B
Engineer: Ray Chang	Contact: http://www.ti.com/support

TEXAS INSTRUMENTS
http://www.ti.com

H1 NY PMS 440 0025 PH

H2 NY PMS 440 0025 PH

H3 NY PMS 440 0025 PH

H4 NY PMS 440 0025 PH

H5 NY PMS 440 0025 PH

H6 NY PMS 440 0025 PH

H7 NY PMS 440 0025 PH

FID1 FID2 FID3

PCB Number: TIDA-00653
PCB Rev: E1

PCB LOGO
Texas Instruments

PCB LOGO
Pb-Free Symbol

PCB LOGO
FCC disclaimer

DANGER HIGH VOLTAGE

DANGER HIGH VOLTAGE

You should delete the nylon screws/standoffs and/or the bumpons as needed for your design (or substitute other parts from Hardware.IntLib). Bumpons are cheaper, but provide less clearance.

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).

Update the Label Text in the Label Table as needed for each Assembly Variant.

You can delete this note too.

LBL1

PCB Label

Size: 0.65" x 0.20 "

Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

CAUTION HOT SURFACE

ZZ1

Label Assembly Note

This Assembly Note is for PCB labels only

ZZ2

Assembly Note

These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3

Assembly Note

These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4

Assembly Note

These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Orderable: EVM_orderable	Designed for: Automotive	Mod. Date: 3/17/2016
TID #: TID	Project Title: Bidirectional DCDC converter	
Number: TIDA-00653 Rev: AA1	Sheet Title: Hardware_ANSI-B	
SVN Rev: Not in version control	Assembly Variant: 001	Sheet: 3 of 3
Drawn By:	File: Hardware_ANSI-B.SchDoc	Size: B
Engineer: Ray Chang	Contact: http://www.ti.com/support	

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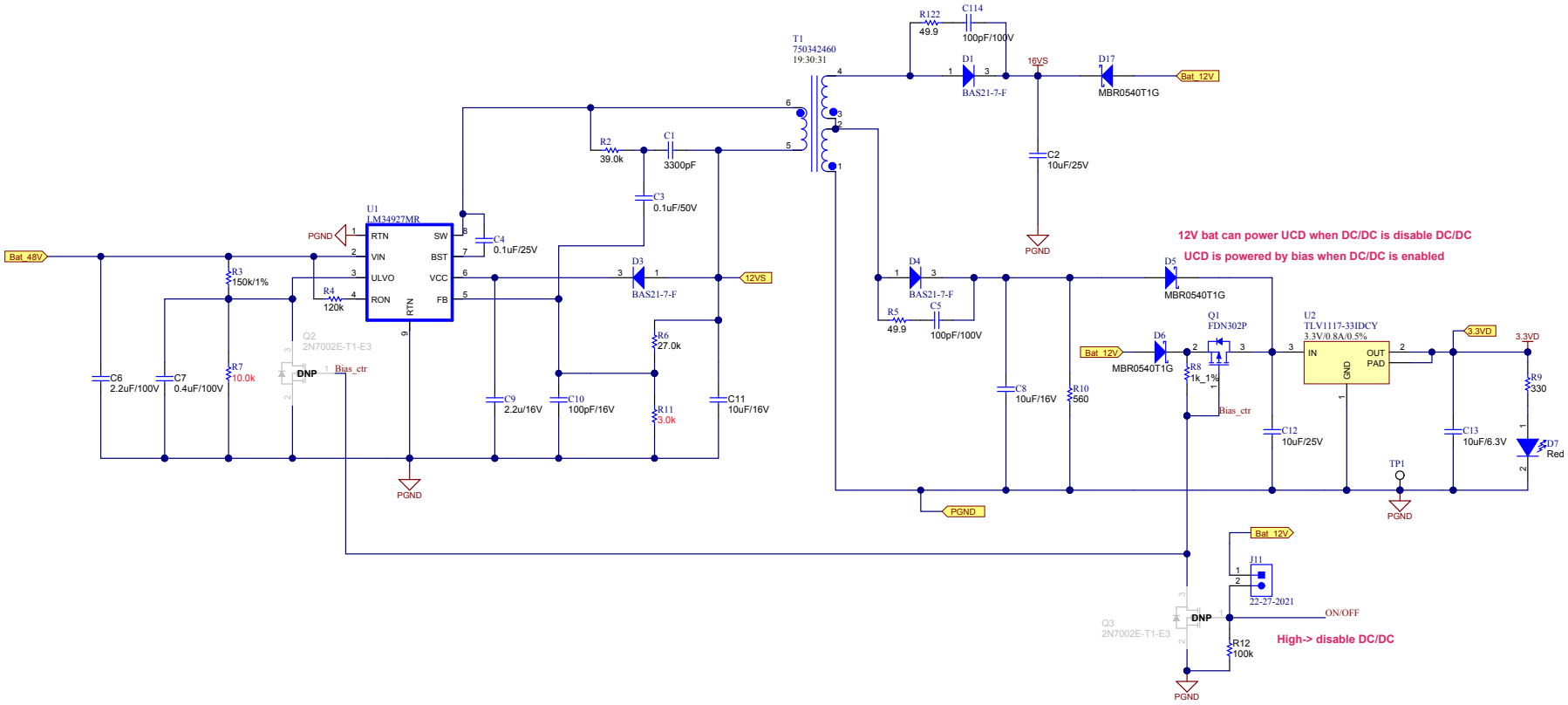
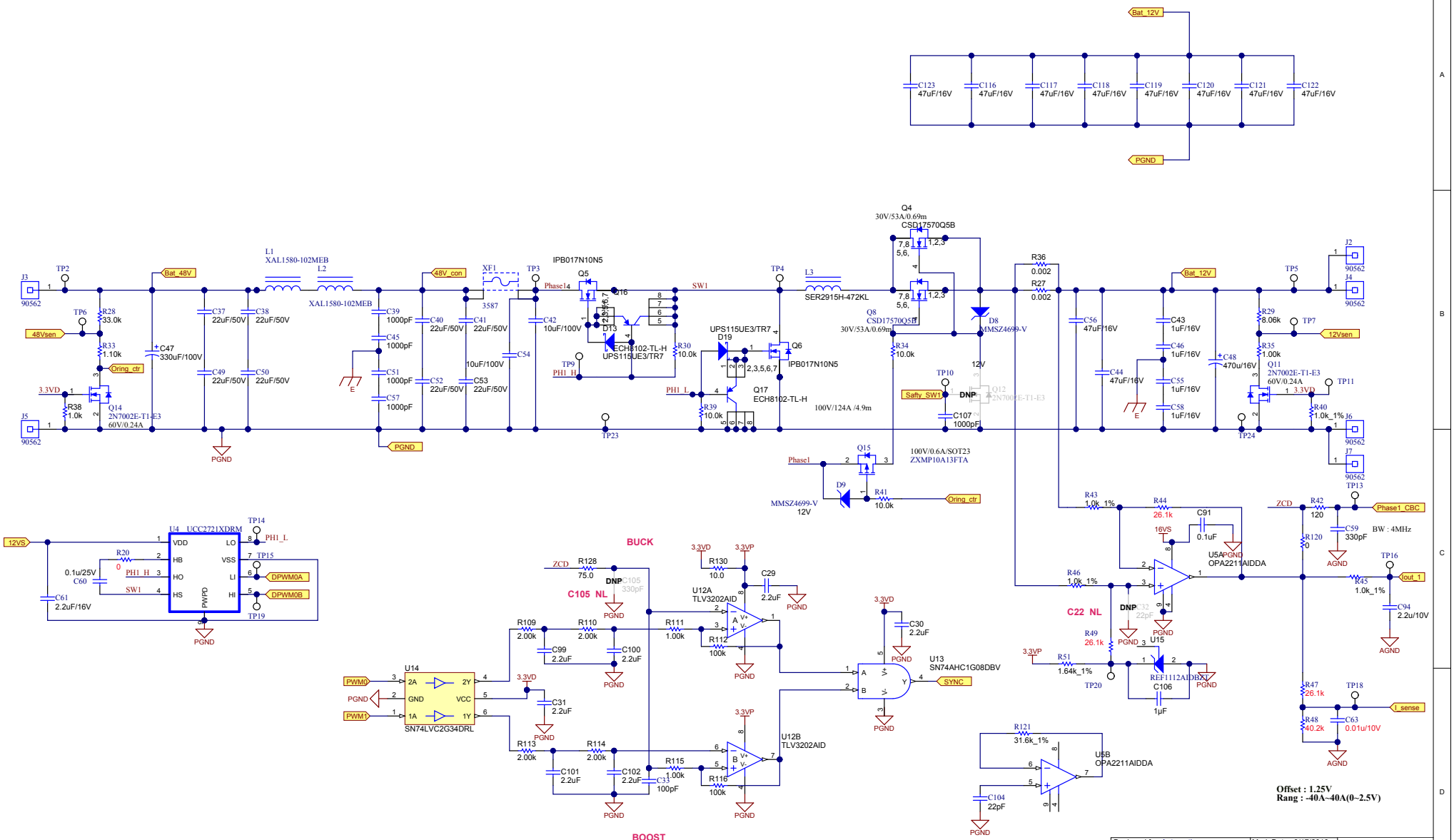


Designed for: Automotive		Mod. Date: 3/17/2016	
Project Title: Bidirectional DCDC converter			
Number: TIDA-00653	Rev: AA1	Sheet Title: Aux Power Supply	
SVN Rev: Not in version control		Assembly Variant: 001	Sheet: 3 of 6
Drawn By:		File: Aux Power Supply.SchDoc	Size: B
Engineer: Ray Chang		Contact: http://www.ti.com/support	

TEXAS INSTRUMENTS
http://www.ti.com



Designed for: Automotive	Mod. Date: 3/17/2016
Project Title: Bidirectional DCDC converter	
Number: TIDA-00653 Rev: AA1	Sheet Title: Phase 1
SVN Rev: Not in version control	Assembly Variant: 001 Sheet: 4 of 6
Drawn By:	File: bidirectional-phase1.SchDoc Size: B
Engineer: Ray Chang	Contact: http://www.ti.com/support

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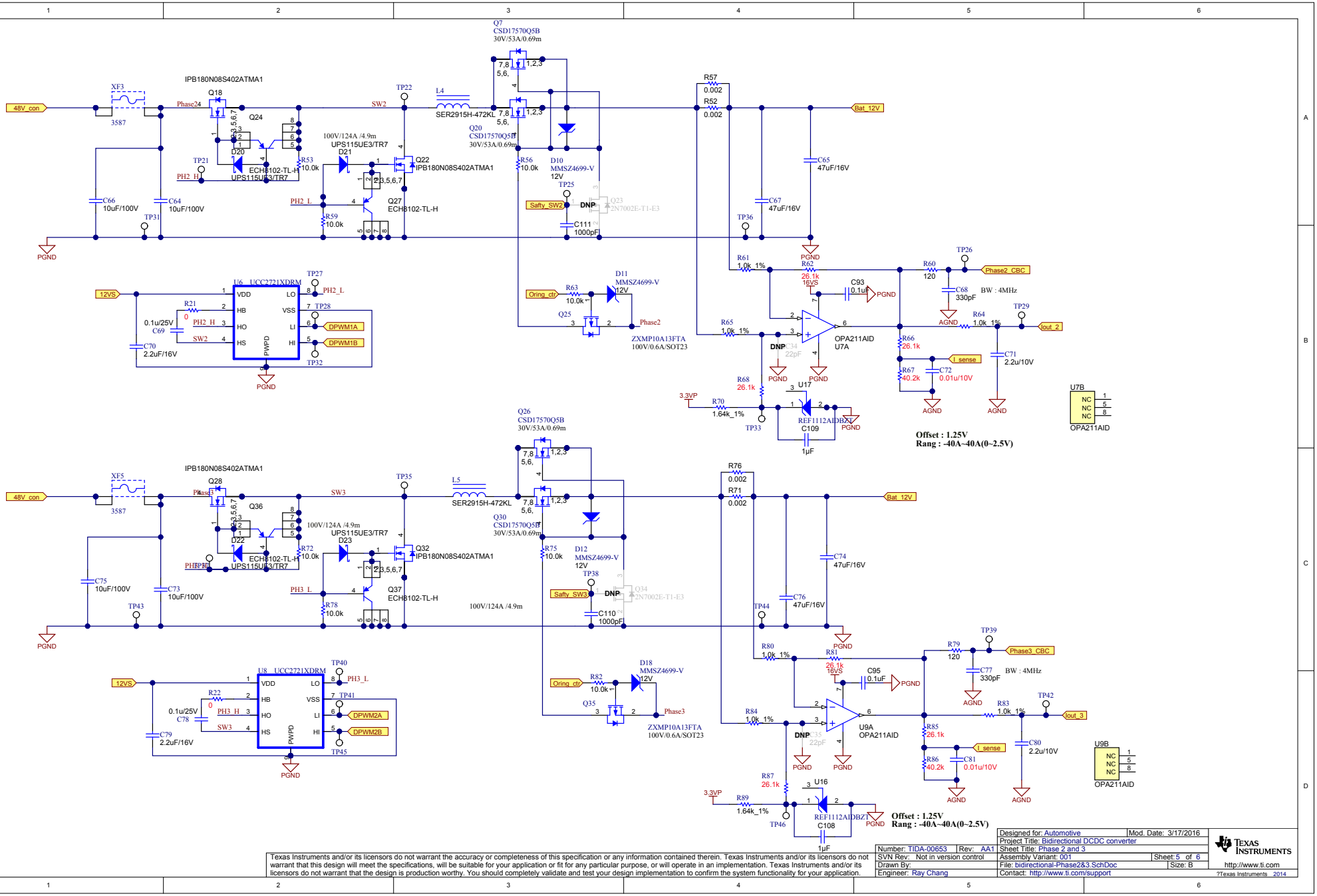

Designed for: Automotive	Mod. Date: 3/17/2016
Project Title: Bidirectional DCDC converter	
Number: TIDA-00663 Rev: AA1	Sheet Title: Phase 2 and 3
SVN Rev: Not in version control	Assembly Variant: 001
Drawn By:	Sheet: 5 of 6
Engineer: Ray Chang	File: bidirectional-Phase2&3.SchDoc Size: B
	Contact: http://www.ti.com/support

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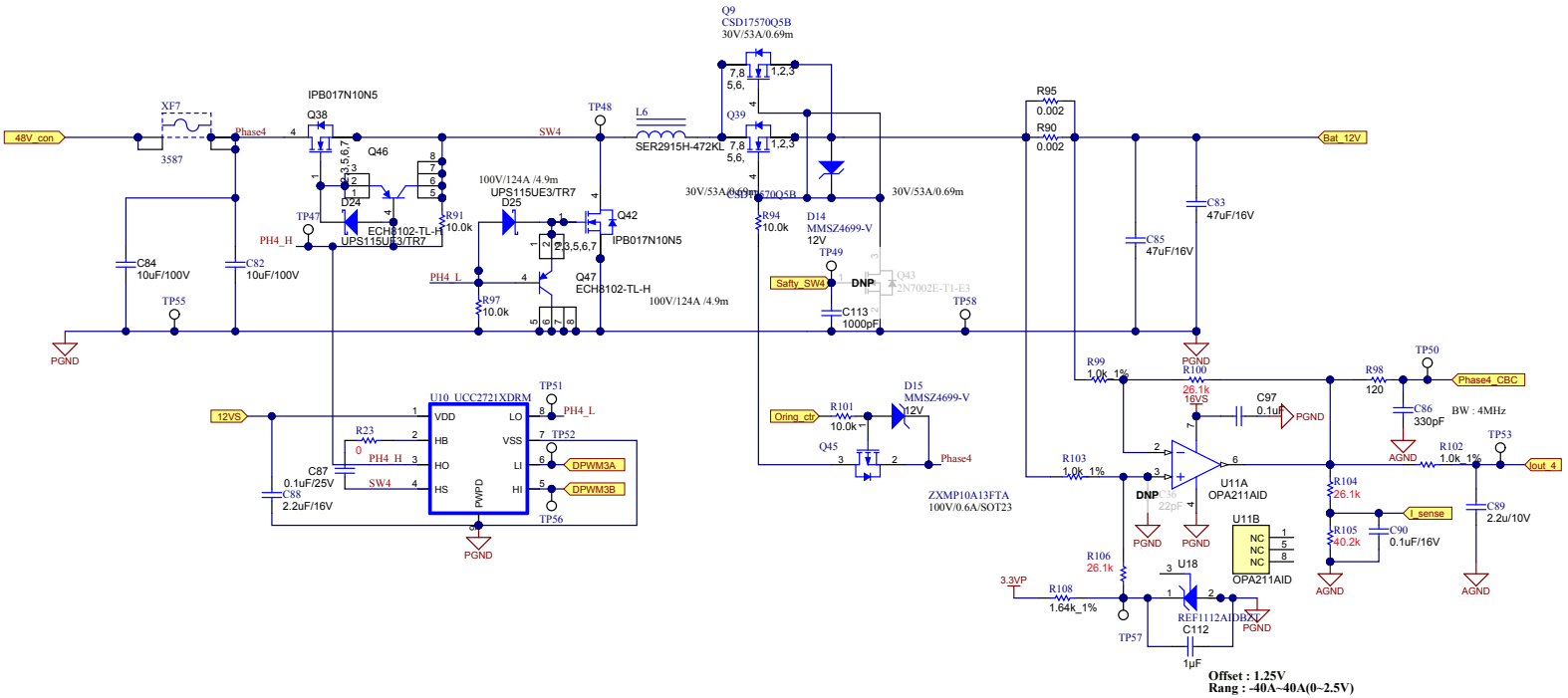

Designed for: Automotive		Mod. Date: 3/17/2016	
Project Title: Bidirectional DCDC converter			
Number: TIDA-00653	Rev: AA1	Sheet Title: Phase 4	
SVN Rev: Not in version control		Assembly Variant: 001	Sheet: 6 of 6
Drawn By:		File: bidirectional-Phase4.SchDoc	Size: B
Engineer: Ray Chang		Contact: http://www.ti.com/support	

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